

Nyquist Rate Analog-to-Digital Converters

Tuesday 9th of March, 2009, 9:15 - 11:00

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Last time – and today, Tuesday 9th of March:

Last time: 12.1 Decoder-Based Converters **12.2 Binary-Scaled Converters** 12.3 Thermometer-Code Converters **12.4 Hybrid Converters** Today – from the following chapters: **13.1 Integrating Converters** 13.2 Successive-Approx. Converters 13.3 Algorithmic (or cyclic) A/D Converters 13.4 Flash (or parallel) converters 13.5 Two-Step A/D converters 13.6 Interpolating A/D Converters (16/3-10) 13.7 Folding A/D Converters (16/3-10) 13.8 Pipelined A/D Converters 13.9 Time-Interleaved A/D Converters







Different A/D Converter Architectures

Low-to-Medium Speed High Accuracy	Medium Speed Medium Accuracy	High Speed Low-to-Medium Accuracy
Integrating	Successive approximation	Flash
Oversampling	Algorithmic	Two-Step
		Interpolating
		Folding
		Pipelined
		Time-interleaved





Different ADCs depending on needs



Figure 1. ADC architectures, applications, resolution, and sampling rates.

Which ADC Architecture Is Right for Your Application?

By Walt Kester [walt.kester@analog.com]



Fig. 2. ADC sample rate vs. ENOB from 1987 to 2005.

IEEE 2005 CUSTOM INTEGRATED CIRCUITS CONFERENCE

Scaling of Analog-to-Digital Converters into Ultra-Deep-Submicron CMOS

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A/D-conversion – Basic Principle



$$V_{ref}(b_1 2^{-1} + b_2 2^{-2} + ... + b_N 2^{-N}) = V_{in} \pm x$$

where $\left(-\frac{1}{2}V_{LSB} < x < \frac{1}{2}V_{LSB}\right)$

- The analog input value is mapped to discrete digital output value
 - Quantization error is introduced





Integrating Converters (13.1)



- $V_x(t) = V_{in} t / RC (V_x ramp derivative depending on V_{in})$
- High linearity and low offset/gain error
- Small amount of circuitry
- Low conversion speed
 - 2^{N+1} * 1/T_{clk} (Worst case)





Integrating Converters



• The digital output is given by the count at the end of T₂

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• The digital output value is independent of the time-constant RC

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Dual slope ADC

POSITIVE INTEGRATOR USED

DUAL- SLUPE ADLS IN

i, = i2

1

durant -

Vinn

RC





Example: 16-bit two-slope ADL with Vin= 3V, Vinex = 4V and Ti= 20ms. RC - constant? Clockf? $f_{clk} = \frac{1}{T_{clk}} = \frac{2^{10}}{20ms} \approx 3.28 \text{ MHz}$ $\frac{v_{inn}}{R} = C \frac{dv_{out}}{dt} = equation (13.15):$ $V_{x} = \frac{V_{in}T_{i}}{RL} = 4V = \frac{3V20ms}{RL}$ 1 RC=15mC

Integrating Converters – careful choice of T1 can attenuate frequency components superimposed on the input signal



- In the above case, 60 Hz and harmonics are attenuated when T1 is an integer multiple of 1/60 Hz.
- Sinc-response with rejection of frequencies multiples of 1/T₁





Successive approx ADC algorithm (13.2)



TOTALS: X = 32 + 8 + 4 + 1 = 45¹⁰ = 101101²

Figure 4. Successive-approximation ADC algorithm using balance scale and binary weights.

Which ADC Architecture Is Right for Your Application?

By Walt Kester [walt.kester@analog.com]

If we have weights of 1 kg, 2 kg, 4 kg, 8 kg, 16 kg, 32 kg and will find the weight of an unknown X assumed to be 45 kg.
101101₂

 $=1^{*}32+0^{*}16+1^{*}8+1^{*}4+0$ $*2+1^{*}1$ $=45_{10}$



Successive-Approximation Converters



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- Uses binary-search
 algorithm
- Accuracy of 2^N requires N steps
- The digital signal accuracy is within +/- 0.5 V_{ref}
- Medium speed
- Medium resolution
- Relatively moderate complexity



DAC-Based Successive Approximation



- \bullet V $_{D/A}$ is adjusted until the value is within 1LSB of V $_{in}$
- Starts with MSB and continues until LSB is found
- Requires DAC, S/H, Comparator and digital logic
- The DAC is typically limiting the resolution





Succ. Approx ADC, example 13.2



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Charge-Redistribution A/D-Converter (unipolar)

 Instead of using a separate DAC and setting it equal to the input voltage (within 1 LSB) as for the DAC based converter from figure 13.5, one can use the error signal equaling the difference between the input signal, V_{in}, and the DAC output, $V_{D/A}$



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Unipolar Charge-Redistribution A/D-Converter







Charge-Redistribution A/D-Converter

- Sample mode:
 - All capacitors charged to Vin while the comparator is reset to its threshold voltage through S₂. The capacitor array is performing S/H operation.
- Hold mode:
 - The comparator is taken out of reset by opening S₂, then all capacitors are switched to ground. V_x is now equal to -V_{in}. Finally S₁ is switched so that V_{ref} can be applied to the capacitors during bit-cycling.
- Bit-cycling:
 - The largest capacitor is switched to V_{ref} . V_x goes to $-V_{in} + V_{ref}/2$. If V_x is negative, then V_{in} is greater than $V_{ref}/2$ and the MSB capacitor is left connected to V_{ref} . Otherwise the MSB capacitor is disconnected and the same procedure is repeated N times





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Signed Charge redistribution A/D



(Fig. 13.8)

- Resembling the unipolar version (Fig. 13.7)
- Assming V_{in} is between +/- $V_{ref}/2$
- Disadvantage: V_{in} attenuated by a factor 2, making noise more of a problem for high resolution ADCs
- Any error in the MSB capacitor causes both offset and a signdependent gain error, leading to INL errors





Resistor-Capacitor Hybrid (figure 13.9 in "J & M")



- Next a succ. approx. conversion is performed to find the two adjacent resistor nodes having voltages larger and smaller than V_{in}
 - One bus will be connected to one node while the other is connected to the other node. All of the capacitors are connected to the bus having the lower voltage.
 - Then a successive approximation using the capacitor-array network is done, starting with the largest capacitor...





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Speed estimate for charge-redistribution converters



Fig. 13.12 Simplified model of a capacitor array during the sampling time.

- RC time constants often limit speed
- Individual time constant due to the 2C cap.: (R_{s1}+R+R_{s2})2C
- (R; bit line)
- Tau_{eq}=(R_{s1}+R+R_{s2})2^NC, for the circuit in fig. 13.12
- For better tha 0.5 LSB accuracy: e⁻
 T/Taueq < 1/(2^N+1), T = charging time
- T > Tau_{eq} (N+1) ln2
 - = 0.69(N+1)Tau_{eq}
- 30 % higher than from Spice simulations ("J & M")



Algorithmic (or Cyclic) A/D Converter



- D Converter (13.3)
 Similar to the Successive approximation converter
- Constant V_{ref}
- Doubles the error each cycle, instead of halving the reference voltage in each cycle, like succ. approx. conv.
- Requires an accurate multiply-by-2 amplifier
- Accuracy can be improved by operating in four cycles (instead of two)
- compact



Ratio-Independent Algorithmic Converter



- Simple circuitry
- Due to the cyclic operation the circuitry are reused in time
- Fully differential circuits normally used

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Ratio-Independent Algorithmic Converter



- The basic idea is to sample the input signal twice using the same capacitor. During the 2nd sampling the charge from the 1st capacitor is stored on a 2nd capacitor whose size is unimportant. After the 2nd sampling both charges are recombined into the 1st capacitor which is then connected between the opamp input and output.
- Does not rely on capacitor matching, is insensitive to amplifier offset.

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Flash (Parallel) Converters (13.4)

- High speed among the fastest
- 2^N comparators in parallel, each connected to different nodes area consuming
- High power consumption
- Thermometer-code output fed into decoder
- Nands used for simpler decoding and error detection (bubble error)
- Differential comparator required to ensure sufficient PSSR
- Top and bottom resistors chosen to create the 0.5 LSB offset in an A/D converter

Flash converter

Any comparator connected to a resistor string nock where Vri is larger than Vin will have a 1 output. One WAND-gate will have a O output. All other NAND-gate outputs will be 1. This also allows for error checking by checking for more than one O output.

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(See tig. 13.16 page Sog)

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Clocked CMOS comparator

- When the clock ("phi") is high, the inverter is set to its bistable point, Vin = Vout (= Vdd/2). The other (left) side of C is charged to V_{ri}.
- When the clock ("phi") goes low, the inverter switches, depending on the voltage difference between V_{ri} and V_{in}. (V_{ri} > V_{in}; 1 output, V_{ri} < V_{in}; 0 output from inv.)
- Differential inverters helps poor PSRR with this simple comparator solution.

Issues in Designing Flash A/D Converters

- Input Capacitive Loading: The large number of comparators connected to Vin results in a large capacitive load on at the input node which increases power and reduces speed
- **Comparator Latch-to-Track Delay:** The internal delay in the comparator when going from latch to track mode
- **Signal and/or Clock Delay:** Differences in signal/clock delay between the comparators may cause errors. Example: A250-MHz, 1-V peak input-sinusoid converted with 8-bit resolution requires a precision of 5ps. Can be reduced by matching the delays and capacitive loads on the signal/clock.
- Substrate and Power-Supply Noise: For a 8-bit converter with Vref=2V only 7.8mV of noise injection is required to introduce an error of 1LSB. The problem can be reduced by proper layout (Shielding, Differential clocks, Separate power supplies, and symmetrical layout)
- Bubble Error Removal: Comparator metastability may introduce wrong thermometer code (a single 1 or 0 in between opposite values)
- Flashback: Caused by latched comparators. When the comparator is switched from track to latch mode a charge glitch is introduced at the input. The problem is reduced by using a preamplifier and input impedance matching

Two-Step (Subranging) A/D Converters (13.5)

- Popular choice for high-speed medium accuracy converters (8-10 b)
- Less area and power consumption than a Flash ADC
- The MSB's are converted during the first step. In the next step the remaining error is converted into the LSB's
- Speed is limited by the Gain Amplifier
- Requires N-bit accuracy for all components (May be relaxed by using Digital Error Correction)

Digital Error Correction for two-step A/D

• The accuracy requirements on the input ADC is relaxed due to the error corr.. 4-bit for MSb converter

Pipelined ADCs (13.5) Once the first stage has completed it's work it immediately starts working on the next sample

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Small area

The pipelined ADC has its origins in the *subranging* architecture, first used in the 1950s. A block diagram of a simple 6-bit, two-stage subranging ADC is shown in Figure 11.

The output of the SHA is digitized by the first-stage 3-bit sub-ADC (SADC)—usually a flash converter. The coarse 3-bit MSB conversion is converted back to an analog signal using a 3-bit sub-DAC (SDAC). Then the SDAC output is subtracted from the SHA output, the difference is amplified, and this "residue signal" is digitized by a second-stage 3-bit SADC to generate the three LSBs of the total 6-bit output word.

R = RANGE OF N2 SADC IDEÀL N1 SADC

Pipelined ADC -example

IEEE JOURNAL OF SOLID-STATE CIRCUITS, VOL. 40, NO. 7, JULY 2005

A Cost-Efficient High-Speed 12-bit Pipeline ADC in 0.18- μ m Digital CMOS

Terje Nortvedt Andersen, Bjørnar Hernes, Member, IEEE, Atle Briskemyr, Frode Telstø, Johnny Bjørnsen, Member, IEEE, Thomas E. Bonnerud, and Øystein Moldsvor

Fig. 7. Power dissipation versus conversion rate. The input frequency and signal swing is 10 MHz and $2V_{P-P}$, respectively.

Nominal sampling rate	110MS/s
Technology	0.18µm digital CMOS
Nominal supply voltage	1.8V
Resolution	12bit
Full scale analog input	2V _{P-P}
Area	0.86mm ²
Power consumption	97mW
DNL	±1.2 LSB
INL	-1.5/+1 LSB
SNR (f_{in} =10MHz)	67.1 dB
SNDR (fin=10MHz)	64.2 dB
SFDR (fin=10MHz)	69.4 dB
ENOB (fin=10MHz)	10.4 bit

MS/s, A is given in mm² and P_{SUP} is given in mW.

Time-Interleaved A/D-converter (13.9)

- Very high speed (figure to the right from "Allen & Holberg")
- f_0 is four timer higher than $f_1 f_4$, which in addition is slightly delayed
- Only the S/H and the MUX must run on the highest frequency
- Tones are introduced at multiples of f₀/N

Time-Interleaved – best compromise between complexity and sampling rate – may be used for different architectures [Elbjornsson '05]

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Dynamic range

- Dynamic range is defined as the power of the maximum input signal range divided by the total power of the quantization noise and distortion
- Often referred to as Signal-to-Noise-and-Distortion range
- S/(N+D)
- SINAD

Analog and digital supply voltages are reduced as technology scales

Fig. 1. Scaling of supply and threshold voltages.

Some ADC trends:

- Limited dynamic range at low supply voltages remains the utmost challenge for highresolution Nyquist converters.
- Oversampling converters will dominate this arena in the future
- Linearity correction with digital correction is becoming prevalent

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Nyquist ADCs at ISSCC; FOM, Effective Number of Bits

Fig. 22. FOM as a function of effective number of bits and technology.

Analog Circuit Design in Nanoscale CMOS Technologies

Classic analog designs are being replaced by digital methods, using nanoscale digital devices, for calibrating circuits, overcoming device mismatches, and reducing bias and temperature dependence.

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BY LANNY L. LEWYN, Life Senior Member IEEE, TROND YTTERDAL, Senior Member IEEE, CARSTEN WULFF, Member IEEE, AND KENNETH MARTIN, Fellow IEEE

- FOM: Figure of Merit
- High-resolution conv.: FOM minimum at about 10⁻¹⁷J/step
- 6-bit ADCs : FOM about 4 orders of magnitude worse than 14 bit converters, suggesting that there is much to be gained by designing more effecient 6-bit ADCs
- Better ENOB reported for 350 nm than 250 nm, 180 nm and 130 nm
- Data from ISSCC up to 2005.

Nyquist ADCs at ISSCC; FOM, Sampling rate

Fig. 23. FOM cliff for Nyquist ADCs in ISSCC 2000–2007.

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- Maximum Sampling frequency (Usually faster is better) and FOM.
- ISSCC 2000-2007 (90 nm, 130 nm, 180 nm technologies)
- Small improvement in sampling frequency in going to finer technologies, mainly due to reduced capacitance.

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SFDR Publication ENOB @ Nyquist Area Supply Technology other Reference Power @Nyquist [mm²] consumpt. voltage year update [nm] Nyquist [dB] [V] rate, [mW] [Ms/s] Gupta et al Time 2006 55 8.5 1000 250 3.5 1.2 130 IEEE JSSC '06 interleaved "Pipelined Wang et al, 2007 2500 24 0.057 1.2 4 130 IEEE Trans. flash" Instr. Meas. Time Ginsburg et al 6 0.9 2007 5 500 1.2 65 IEEE JSSC '07 interleaved succ. approx Wu et al, IEEE Switched 8 2007 100 30 2.04 1.0 180 JSSC '07 opamp pipelined Li et al, IEEE pipelined 0.7 2008 10 30 22 1.8 180 JSSC '08 Chae, JSSCC Delta-sigma 2009 81 13 0.073 0.7 180 Feb.09 "folding flash" Verbruggen, 2009 27.5 4.3 1750 2.2 0.02 1.0 90 JSSCC, Mar. '09 Continous time TCAS-II, Jan. 2009 10 1.2 12.2 0.354 3.3 350 sigma delta '09

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Sampling-time uncertainty

•Variation in output voltage caused by variations in the time of sampling

Consider the following input signal:

$$V_{\rm in} = \frac{V_{\rm ref}}{2} \sin(2\pi f_{\rm in} t)$$

If the variation in sampling time is $\,\Delta t\,$, following equation must be satisfied to keep $\Delta V\,$ less than 1LSB

$$\Delta t < \frac{V_{LSB}}{\pi f_{in} V_{ref}} = \frac{1}{2^N \pi f_{in}}$$

Additional litterature

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- Jonas Elbornsson: White paper on parallel successive approximation ADC, Mathcore Engineering AB, 2005.
- R. Gregorian, G. Temes: Analog MOS Integrated Circuits for Signal Processing, Wiley, 1986
- D. M.Gingrich Lecture Notes, University of Alberta, Canada <u>http://www.piclist.com/images/ca/ualberta/phys/www/http/~gingrich/phys395/notes/phys395.html</u>
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- Y. Chiu, B. Nicolic, P. R. Gray: Scaling of Analog-to-Digital Converters into Ultra-Deep-Submicron CMOS, Proceedings of Custom Integrated Circuits Conference, 2005.
- Lecture Notes, University of California, Berkeley, EE247 Analog Digital Interface Integrated Circuits, Fall 07;http://inst.eecs.berkeley.edu/~ee247/fa07/
- Lanny L. Lewyn, Trond Ytterdal, Carsten Wulff, Kenneth Martin: "Analog Circuit Design in Nanoscale CMOS Technologies", Proceedings of the IEEE, October 2009.
- James L. McCreary, Paul R. Gray: "All-MOS Charge Redistribution Analog-to-Digital Conversion Techniques part 1", IEEE Journal of Solid-State circuits, December 1975.

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Next Tuesday (10/3-08):

Rest of chapter 13.

Chapter 14 Oversampling Converters

Figure 1. ADC architectures, applications, resolution, and sampling rates.

Figure 6. Noise-spectrum effects of the fundamental concepts used in Σ - Δ : oversampling, digital filtering, noise shaping, and decimation.

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Analog Layout - mismatch

- "...The ratio between two similar components on the same integrated circuit can be controlled to better than +/- 1 %, and in many cases, to better than +/- 0.1 %. Devices specifically constructed to obtain a known, constant ratio are called matched devices."
- "Matching the Achilles Heel of Analog" (Chris Diorio) 10. mars 2010

Some companies located in Norway, doing (or that have done) full custom data converter designs:

- Analog Concepts (Trondheim)
- Arctic Silicon Devices (Trondheim)
- Atmel Norway (Trondheim)
- Energy Micro (Oslo)
- GE Vingmed Ultrasound (Horten)
- Nordic Semiconductors (Trondheim, Oslo)
- Novelda (Oslo)
- Micrel (Oslo)
- Sintef (Trondheim, Oslo)
- Texas Instruments (Oslo)

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Metastability in FFS (<u>http://www.asic-world.com/tidbits/metastablity.html</u>) To avoid M. in comparators: Make gain high, increase current levels.

Solution (19) What is metastability?

Whenever there are setup and hold time violations in any flip-flop, it enters a state where its output is unpredictable: this state is known as metastable state (quasi stable state); at the end of metastable state, the flip-flop settles down to either '1' or '0'. This whole process is known as metastability. In the figure below Tsu is the setup time and Th is the hold time. Whenever the input signal D does not meet the Tsu and Th of the given D flip-flop, metastability occurs.

When a flip-flop is in metastable state, its output oscillate between '0' and '1' as shown in the figure below (here the flip-flop output settles down to '0'). How long it takes to settle down, depends on the technology of the flip-flop.

The approximate equation which describes the output voltage, $V_0(t)$ is given by:

$$V_{\rm O}(t) = \Delta V_{\rm IN} A e^{t/\tau},$$
 Eq. 1

where ΔV_{IN} = the differential input voltage at the time of latching, A = the gain of the preamp at the time of latching, τ = regeneration time constant of the latch, and t = the time that has elapsed after the comparator output is latched (see References 2 and 3).

For small differential input voltages, the output takes longer to reach a valid logic level. If the output data is read when it lies between the "valid logic 1" and the "valid logic 0" region, the data can be in error. If the differential input voltage is exactly zero, and the comparator is perfectly balanced at the time of latching, the time required to reach a valid logic level can be quite long (theoretically infinite). However, comparator hysteresis and input noise makes this condition highly unlikely. The effects of invalid logic levels out of the comparator are different depending upon how the comparator is used in the actual ADC.

From a design standpoint, comparator metastability can be minimized by making the gain (A) high, minimizing the regeneration time constant (τ) by increasing the gain-bandwidth of the latch, and allowing sufficient time (t), for the output of the comparator to settle to a valid logic level. It is not the purpose of this discussion to analyze the complex tradeoffs between speed,

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